

# TPCP8012

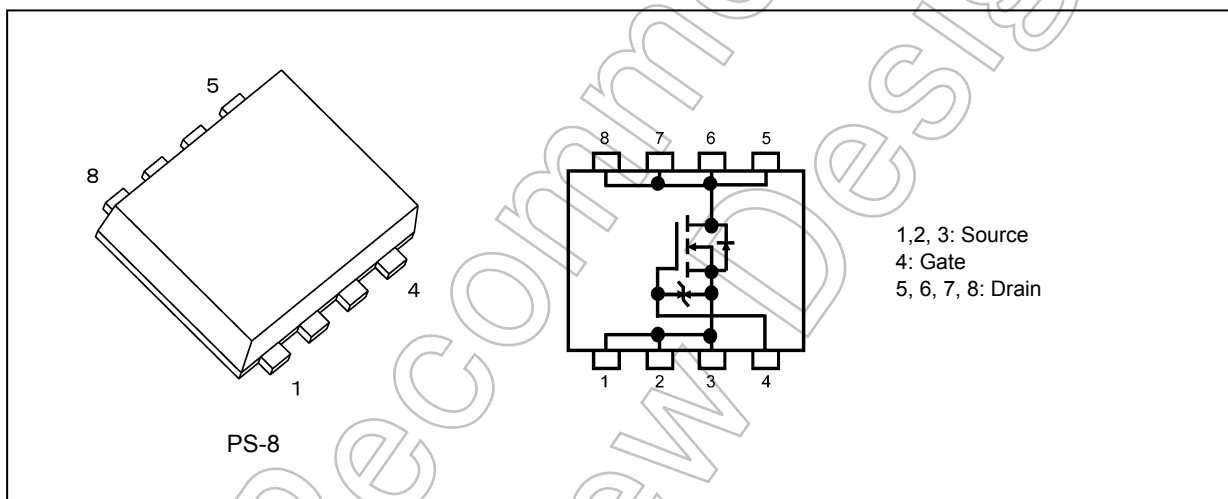
## 1. Applications

- Motor Drivers
- Mobile Equipment

## 2. Features

- (1) AEC-Q101 qualified
- (2) Small, thin package
- (3) Small gate charge :  $Q_{SW} = 10 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 16.2 \text{ m}\Omega \text{ (typ.) (} V_{GS} = 10 \text{ V)}$
- (5) Low leakage current:  $I_{DSS} = 10 \text{ }\mu\text{A (max) (} V_{DS} = 60 \text{ V)}$
- (6) Enhancement mode:  $V_{th} = 2 \text{ to } 3 \text{ V (} V_{DS} = 10 \text{ V, } I_D = 1 \text{ mA)}$

## 3. Packaging and Internal Circuit



Start of commercial production

2012-10

#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	$V_{\text{DSS}}$	60	V
Gate-source voltage	$V_{\text{GSS}}$	$\pm 20$	
Drain current (DC) (Note 1)	$I_{\text{D}}$	8	A
Drain current (pulsed) (Note 1)	$I_{\text{DP}}$	32	
Power dissipation ( $t = 5$ s) (Note 2)	$P_{\text{D}}$	2.01	W
Power dissipation ( $t = 5$ s) (Note 3)	$P_{\text{D}}$	1	W
Single-pulse avalanche energy (Note 4)	$E_{\text{AS}}$	72.1	mJ
Avalanche current	$I_{\text{AR}}$	8	A
Channel temperature (Note 5)	$T_{\text{ch}}$	175	$^\circ\text{C}$
Storage temperature (Note 5)	$T_{\text{stg}}$	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

#### 5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-ambient thermal resistance ( $t = 5$ s) (Note 2)	$R_{\text{th(ch-a)}}$	74.6	$^\circ\text{C/W}$
Channel-to-ambient thermal resistance ( $t = 5$ s) (Note 3)	$R_{\text{th(ch-a)}}$	150	$^\circ\text{C/W}$

Note 1: Ensure that the channel temperature does not exceed  $175^\circ\text{C}$ .

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4:  $V_{\text{DD}} = 25$  V,  $T_{\text{ch}} = 25^\circ\text{C}$  (initial),  $L = 1.531$  mH,  $R_{\text{G}} = 1$   $\Omega$ ,  $I_{\text{AR}} = 8$  A

Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

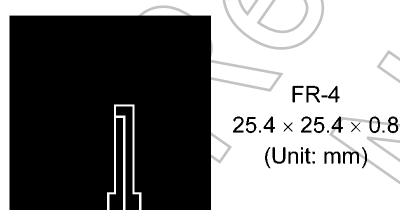


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

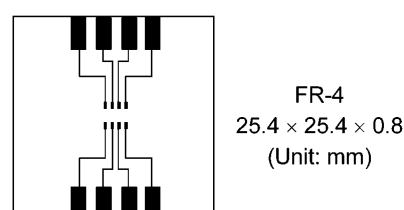


Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

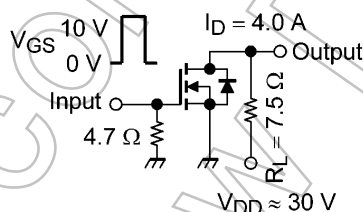
## 6. Electrical Characteristics

### 6.1. Static Characteristics ( $T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16\text{ V}$ , $V_{DS} = 0\text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain cut-off current	$I_{DSS}$	$V_{DS} = 60\text{ V}$ , $V_{GS} = 0\text{ V}$	—	—	10	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}$ , $V_{GS} = 0\text{ V}$	60	—	—	V
Drain-source breakdown voltage	$V_{(BR)DSX}$	$I_D = 10\text{ mA}$ , $V_{GS} = -20\text{ V}$	40	—	—	
Gate threshold voltage	$V_{th}$	$V_{DS} = 10\text{ V}$ , $I_D = 1\text{ mA}$	2	2.5	3	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 6\text{ V}$ , $I_D = 4\text{ A}$	—	18.2	29.1	$\text{m}\Omega$
		$V_{GS} = 10\text{ V}$ , $I_D = 4\text{ A}$	—	16.2	20.2	

### 6.2. Dynamic Characteristics ( $T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	$C_{iss}$	$V_{DS} = 10\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$	—	1160	—	pF
Reverse transfer capacitance	$C_{rss}$		—	120	—	
Output capacitance	$C_{oss}$		—	200	—	
Switching time (rise time)	$t_r$	See Figure 6.2.1	—	5.6	—	ns
Switching time (turn-on time)	$t_{on}$		—	13	—	
Switching time (fall time)	$t_f$		—	10	—	
Switching time (turn-off time)	$t_{off}$		—	37	—	



Duty  $\leq 1\%$ ,  $t_w = 10\text{ }\mu\text{s}$

Fig. 6.2.1 Switching Time Test Circuit

### 6.3. Gate Charge Characteristics ( $T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	$Q_g$	$V_{DD} \approx 48\text{ V}$ , $V_{GS} = 10\text{ V}$ , $I_D = 8\text{ A}$	—	26.6	—	nC
Gate-source charge 1	$Q_{gs1}$		—	3.9	—	
Gate-drain charge	$Q_{gd}$		—	8.7	—	
Gate switch charge	$Q_{sw}$		—	10	—	

### 6.4. Source-Drain Characteristics ( $T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (Note 6)	$I_{DRP}$	—	—	—	32	A
Diode forward voltage	$V_{DSF}$	$I_{DR} = 8\text{ A}$ , $V_{GS} = 0\text{ V}$	—	—	-1.2	V

Note 6: Ensure that the channel temperature does not exceed  $175^\circ\text{C}$ .

## 7. Marking

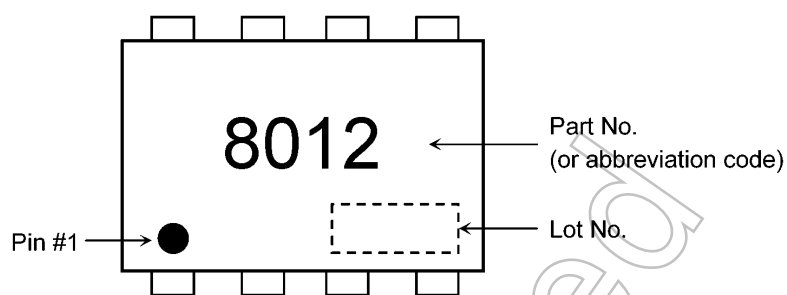
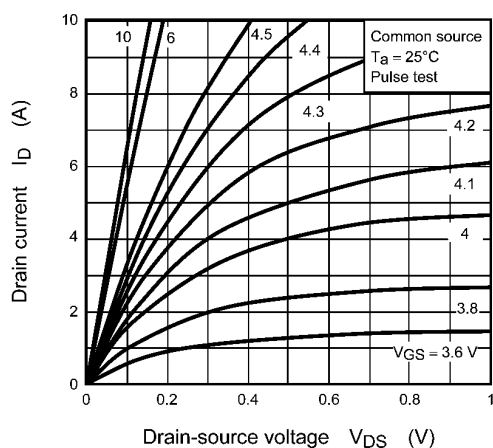


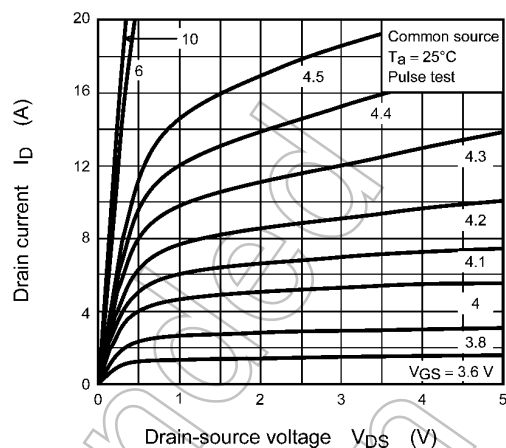
Fig. 7.1 Marking

Not Recommended for New Design

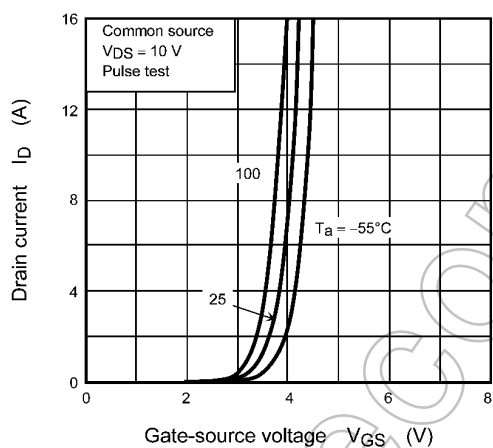
# 8. Characteristics Curves (Note)



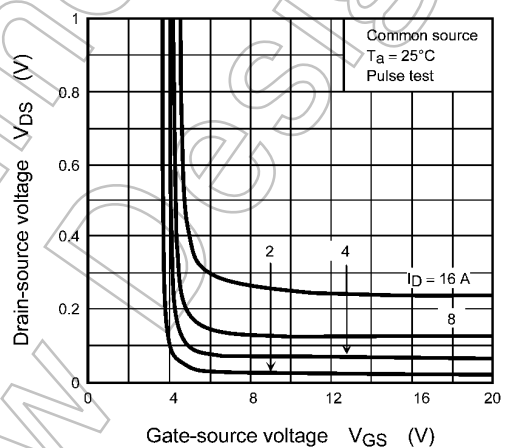
**Fig. 8.1  $I_D - V_{DS}$**



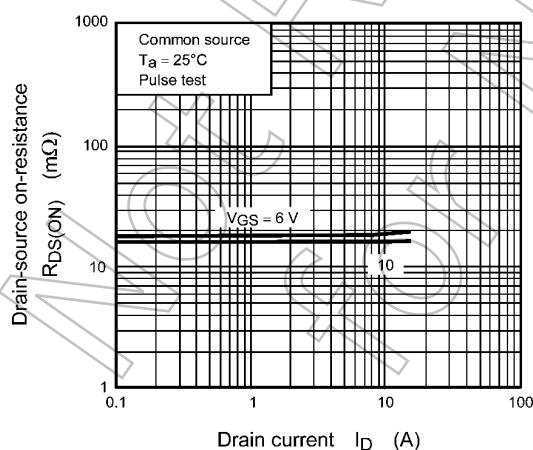
**Fig. 8.2  $I_D - V_{DS}$**



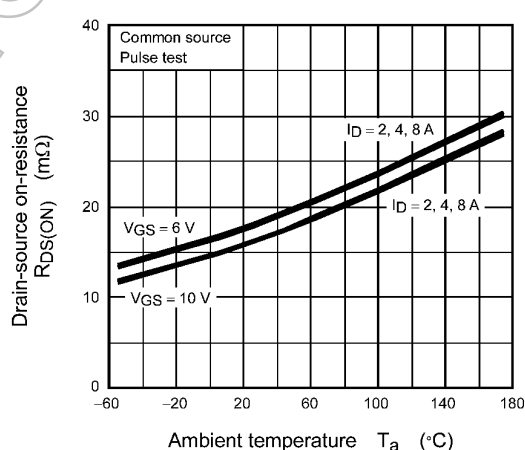
**Fig. 8.3  $I_D - V_{GS}$**



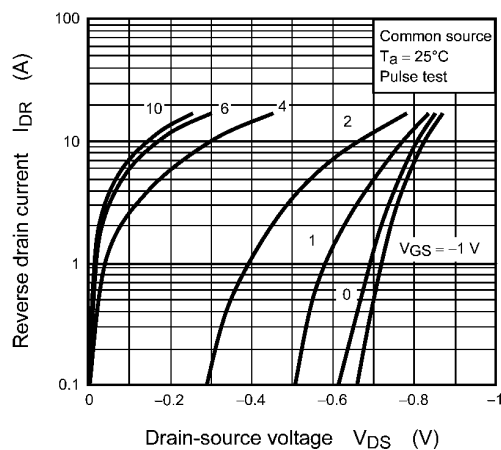
**Fig. 8.4  $V_{DS} - V_{GS}$**



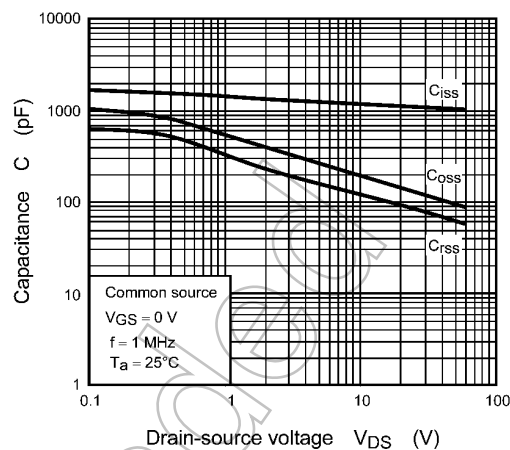
**Fig. 8.5  $R_{DS(ON)} - I_D$**



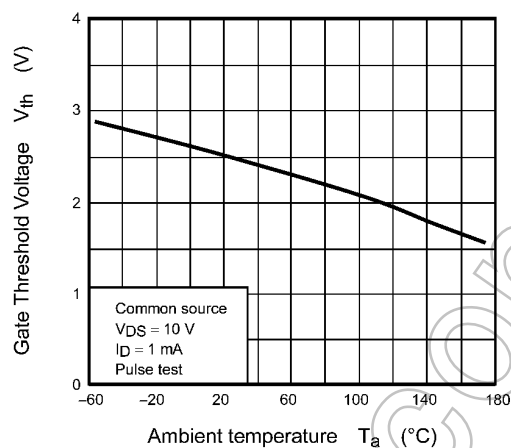
**Fig. 8.6  $R_{DS(ON)} - T_a$  (Note 7)**



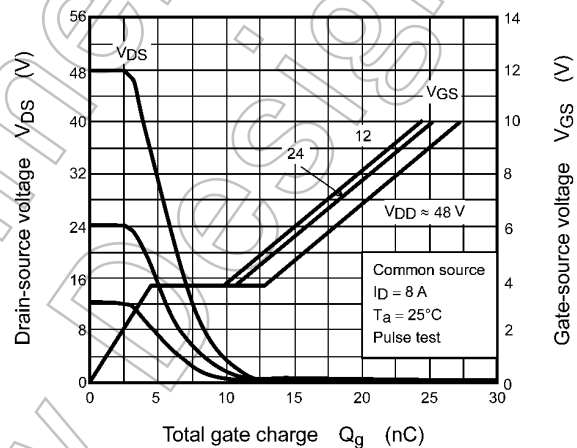
**Fig. 8.7  $I_{DR} - V_{DS}$**



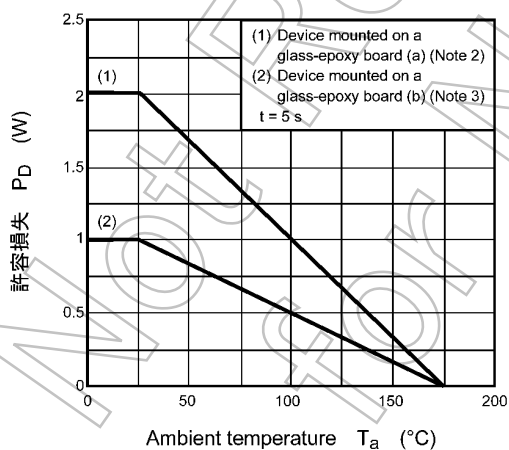
**Fig. 8.8 Capacitance -  $V_{DS}$**



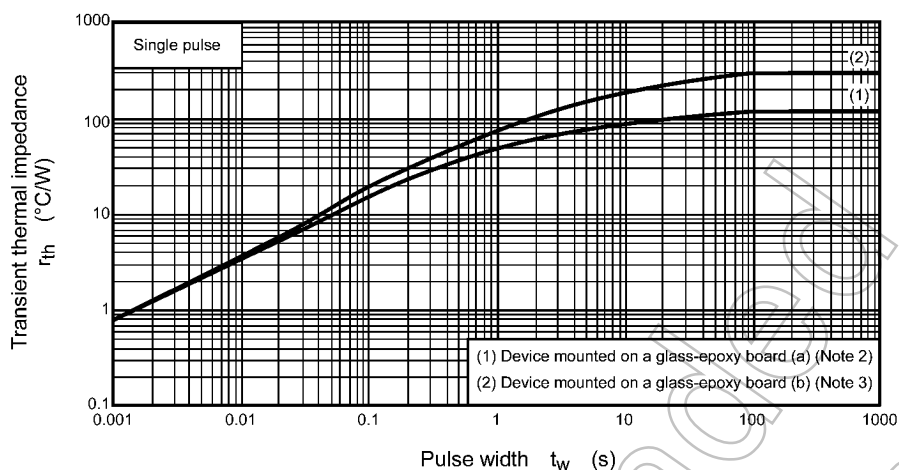
**Fig. 8.9  $V_{th} - T_a$  (Note 7)**



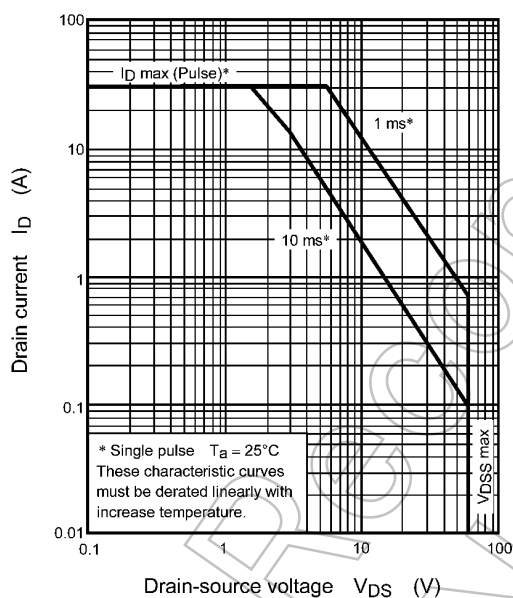
**Fig. 8.10 Dynamic Input/Output Characteristics**



**Fig. 8.11  $P_D - T_a$  (Note 7)  
 (Guaranteed Maximum)**



**Fig. 8.12  $r_{th} - t_w$**   
(Guaranteed Maximum)



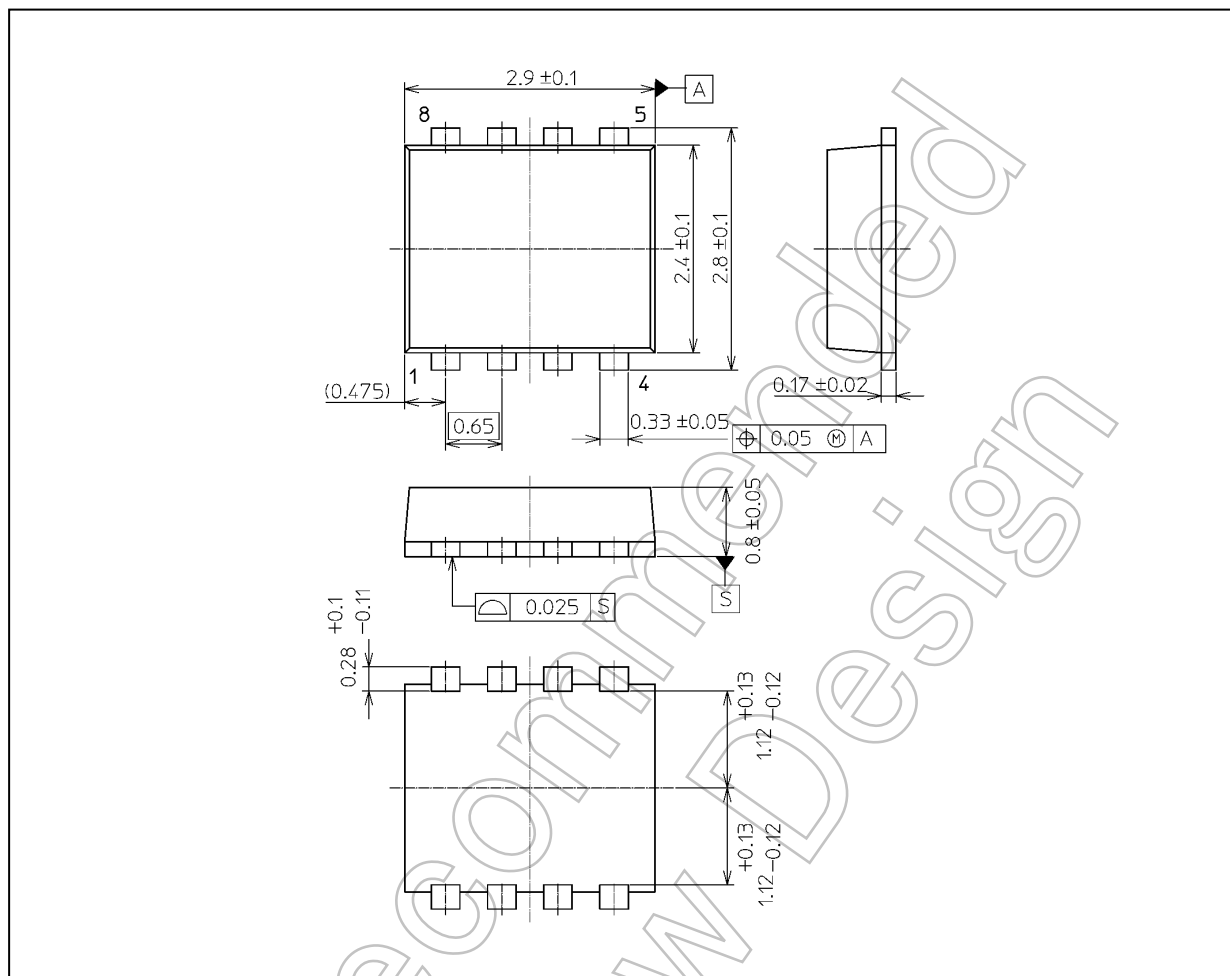
**Fig. 8.13 Safe Operating Area**  
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Note 7: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

**Package Dimensions**

Unit: mm



Weight: 0.017 g (typ.)

Package Name(s)
TOSHIBA: 2-3V1S
Nickname: PS-8



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